



3.3V CMOS 12-BIT SYNCHRONOUS BUS EXCHANGER WITH BUS-HOLD

IDT74ALVCH16276

FEATURES:

- 0.5 MICRON CMOS Technology
- Typical $t_{sk(0)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015;
> 200V using machine model (C = 200pF, R = 0)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP,
and 0.40mm pitch TVSOP packages
- Extended commercial range of -40°C to $+85^{\circ}\text{C}$
- $V_{CC} = 3.3\text{V} \pm 0.3\text{V}$, Normal Range
- $V_{CC} = 2.7\text{V}$ to 3.6V , Extended Range
- $V_{CC} = 2.5\text{V} \pm 0.2\text{V}$
- CMOS power levels (0.4 μW typ. static)
- Rail-to-Rail output swing for increased noise margin

Drive Features for ALVCH16276:

- High Output Drivers: $\pm 24\text{mA}$
- Suitable for heavy loads

APPLICATIONS:

- 3.3V High Speed Systems
- 3.3V and lower voltage computing systems

DESCRIPTION:

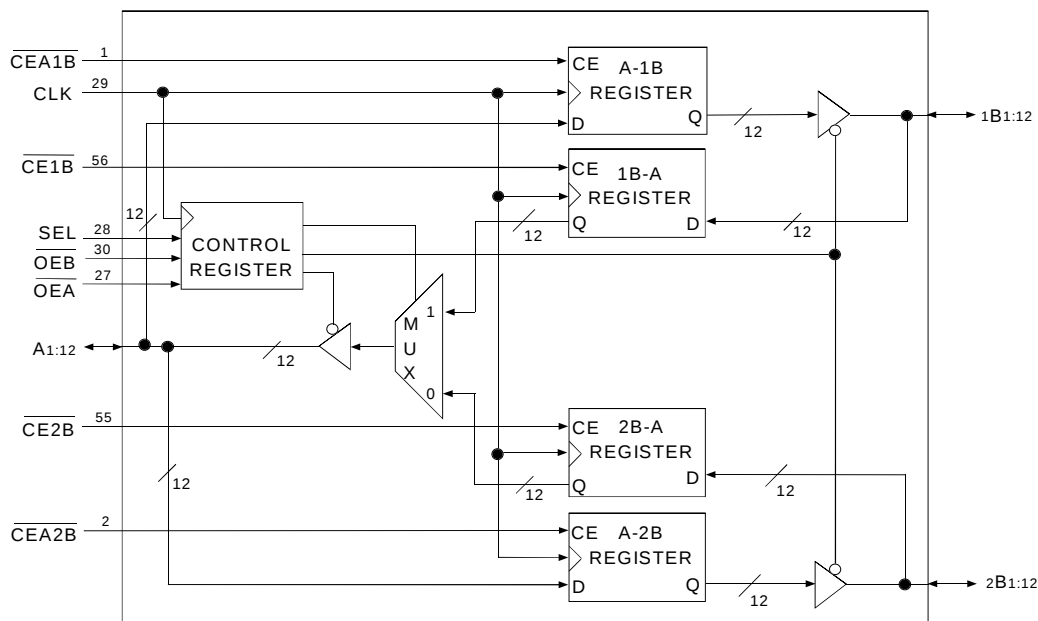
This 12-bit synchronous bus exchanger is built using dual metal CMOS technology. The ALVCH16276 device is a high-speed, bidirectional, 12-bit, registered, bus multiplexer for use in synchronous memory interleaving applications. All registers have a common clock and use a clock enable ($\overline{\text{CE}}_{\text{xxx}}$) on each data register to control data sequencing. The output enables and mux select ($\overline{\text{OEA}}$, $\overline{\text{OEB}}$ and SEL) are also under synchronous control allowing direction changes to be edge triggered events.

The ALVCH16276 has three 12-bit ports. Data may be transferred between the A port and either/both of the B ports. The clock enable ($\overline{\text{CE}}_{1\text{B}}$, $\overline{\text{CE}}_{2\text{B}}$, $\overline{\text{CEA}}_{1\text{B}}$ and $\overline{\text{CEA}}_{2\text{B}}$) inputs control data storage. Both B ports have a common output enable ($\overline{\text{OEB}}$) to aid in synchronously loading the B registers from the B port.

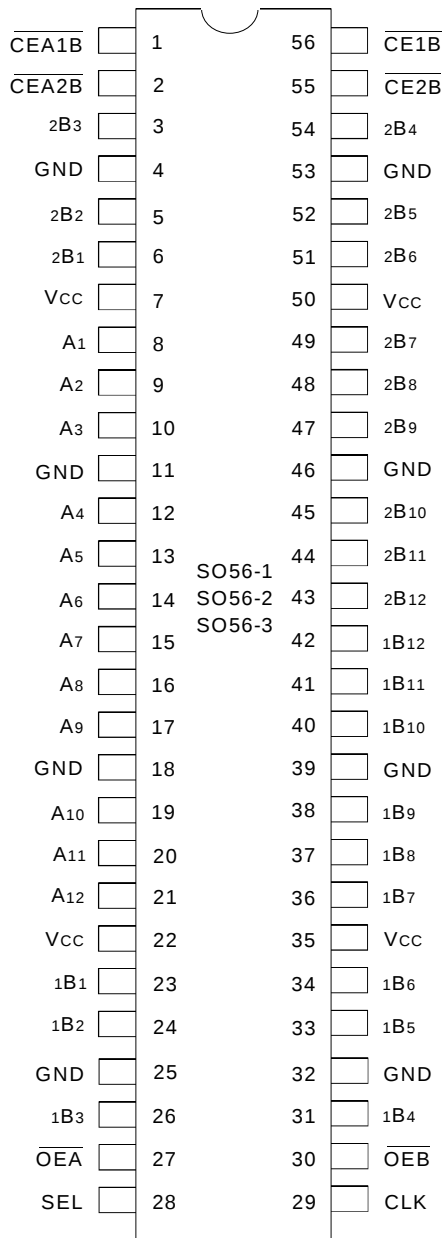
The ALVCH16276 has been designed with a $\pm 24\text{mA}$ output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

The ALVCH16276 has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.

Functional Block Diagram



PIN CONFIGURATION



SSOP/
TSSOP/TVSOP
TOP VIEW

ABSOLUTE MAXIMUM RATING (1)

Symbol	Description	Max.	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	– 0.5 to + 4.6	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	– 0.5 to V _{CC} + 0.5	V
TSTG	Storage Temperature	– 65 to + 150	°C
I _{OUT}	DC Output Current	– 50 to + 50	mA
I _{IK}	Continuous Clamp Current, V _I < 0 or V _I > V _{CC}	± 50	mA
I _{OK}	Continuous Clamp Current, V _O < 0	– 50	mA
I _{CC} I _{SS}	Continuous Current through each V _{CC} or GND	±100	mA

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NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- V_{CC} terminals.
- All terminals except V_{CC}.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	5	7	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	7	9	pF
C _{I/O}	I/O Port Capacitance	V _{IN} = 0V	7	9	pF

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NOTE:

- As applicable to the device type.

PIN DESCRIPTION

Pin Names	I/O	Description
Ax(1:12)	I/O	Bidirectional Data Port A. Usually connected to the CPU's Address/Data bus. ⁽¹⁾
1Bx(1:12)	I/O	Bidirectional Data Port 1B. Usually connected to the even path or even bank of memory. ⁽¹⁾
2Bx(1:12)	I/O	Bidirectional Data Port 2B. Usually connected to the odd path or odd bank of memory. ⁽¹⁾
CLK	I	Clock Input
$\overline{\text{CEA1B}}$	I	Clock Enable Input for the A-1B Register. If $\overline{\text{CEA1B}}$ is LOW during the rising edge of CLK, data will be clocked into register A-1B (Active LOW).
$\overline{\text{CEA2B}}$	I	Clock Enable Input for the A-2B Register. If $\overline{\text{CEA2B}}$ is LOW during the rising edge of CLK, data will be clocked into register A-2B (Active LOW).
$\overline{\text{CE1B}}$	I	Clock Enable Input for the 1B-A Register. If $\overline{\text{CE1B}}$ is LOW during the rising edge of CLK, data will be clocked into register 1B-A (Active LOW).
$\overline{\text{CE2B}}$	I	Clock Enable Input for the 2B-A Register. If $\overline{\text{CE2B}}$ is LOW during the rising edge of CLK, data will be clocked into register 2B-A (Active LOW).
SEL	I	1B or 2B Port Selection. When HIGH during the rising edge of CLK, SEL enables data transfer from 1B Port to A Port. When LOW during the rising edge of CLK, SEL enables data transfer from 2B Port to A Port.
$\overline{\text{OEA}}$	I	Synchronous Output Enable for A Port (Active LOW).
$\overline{\text{OEB}}$	I	Synchronous Output Enable for 1B Port and 2B Port (Active LOW).

NOTE:

- These pins have "Bus-Hold." All other pins are standard inputs, outputs, or I/Os.

FUNCTION TABLES⁽¹⁾

Inputs							Output
1Bx	2Bx	SEL	$\overline{\text{CE1B}}$	$\overline{\text{CE2B}}$	$\overline{\text{OEA}}$	CLK	Ax
H	X	H	L	X	L	—	H
L	X	H	L	X	L	—	L
X	X	H	H	X	L	—	Ao ⁽²⁾
X	H	L	X	L	L	—	H
X	L	L	X	L	L	—	L
X	X	L	X	H	L	—	Ao ⁽²⁾
X	X	X	X	X	H	—	Z

Inputs					Outputs	
Ax	$\overline{\text{CEA1B}}$	$\overline{\text{CEA2B}}$	$\overline{\text{OEB}}$	CLK	1Bx	2Bx
H	L	L	L	—	H	H
L	L	L	L	—	L	L
H	L	H	L	—	H	Bo ⁽²⁾
L	L	H	L	—	L	Bo ⁽²⁾
H	H	L	L	—	Bo ⁽²⁾	H
L	H	L	L	—	Bo ⁽²⁾	L
X	H	H	L	—	Bo ⁽²⁾	Bo ⁽²⁾
X	X	X	H	—	Z	Z
X	X	X	L	—	Active	Active

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
- Output level before the indicated steady-state input conditions were established.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: TA = – 40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
V _{IH}	Input HIGH Voltage Level	V _{CC} = 2.3V to 2.7V		1.7	—	—	V
		V _{CC} = 2.7V to 3.6V		2	—	—	
V _{IL}	Input LOW Voltage Level	V _{CC} = 2.3V to 2.7V		—	—	0.7	V
		V _{CC} = 2.7V to 3.6V		—	—	0.8	
I _{IH}	Input HIGH Current	V _{CC} = 3.6V	V _I = V _{CC}	—	—	± 5	μA
I _{IL}	Input LOW Current	V _{CC} = 3.6V	V _I = GND	—	—	± 5	
I _{OZH}	High Impedance Output Current (3-State Output pins)	V _{CC} = 3.6V	V _O = V _{CC}	—	—	± 10	μA
I _{OZL}			V _O = GND	—	—	± 10	μA
V _{IK}	Clamp Diode Voltage	V _{CC} = 2.3V, I _{IN} = – 18mA		—	– 0.7	– 1.2	V
V _H	Input Hysteresis	V _{CC} = 3.3V		—	100	—	mV
I _{CCL} I _{CCH} I _{CCZ}	Quiescent Power Supply Current	V _{CC} = 3.6V V _{IN} = GND or V _{CC}		—	0.1	40	μA
ΔI _{CC}	Quiescent Power Supply Current Variation	One input at V _{CC} – 0.6V, other inputs at V _{CC} or GND		—	—	750	μA

NOTE:

1. Typical values are at V_{CC} = 3.3V, +25°C ambient.

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BUS-HOLD CHARACTERISTICS

Symbol	Parameter ⁽¹⁾	Test Conditions		Min.	Typ. ⁽²⁾	Max.	Unit
I _{BHH} I _{BHL}	Bus-Hold Input Sustain Current	V _{CC} = 3.0V	V _I = 2.0V	– 75	—	—	μA
			V _I = 0.8V	75	—	—	
I _{BHH} I _{BHL}	Bus-Hold Input Sustain Current	V _{CC} = 2.3V	V _I = 1.7V	– 45	—	—	μA
			V _I = 0.7V	45	—	—	
I _{BHHO} I _{BHLO}	Bus-Hold Input Overdrive Current	V _{CC} = 3.6V	V _I = 0 to 3.6V	—	—	± 500	μA

NOTES:

1. Pins with Bus-hold are identified in the pin description.
2. Typical values are at V_{CC} = 3.3V, +25°C ambient.

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OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	VCC = 2.3V to 3.6V	IOH = - 0.1mA	VCC - 0.2	—	V
		VCC = 2.3V	IOH = - 6mA	2	—	
		VCC = 2.3V	IOH = - 12mA	1.7	—	
		VCC = 2.7V		2.2	—	
		VCC = 3.0V		2.4	—	
		VCC = 3.0V	IOH = - 24mA	2	—	
VOL	Output LOW Voltage	VCC = 2.3V to 3.6V	IOL = 0.1mA	—	0.2	V
		VCC = 2.3V	IOL = 6mA	—	0.4	
			IOL = 12mA	—	0.7	
		VCC = 2.7V	IOL = 12mA	—	0.4	
		VCC = 3.0V	IOL = 24mA	—	0.55	

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NOTE:

1. VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate VCC range. TA = - 40°C to + 85°C.

OPERATING CHARACTERISTICS, TA = 25°C

Symbol	Parameter	Test Conditions	VCC = 2.5V ± 0.2V	VCC = 3.3V ± 0.3V	Unit
			Typical	Typical	
CPD	Power Dissipation Capacitance Outputs enabled	CL = 0pF, f = 10Mhz	55	59	pF
CPD	Power Dissipation Capacitance Outputs disabled		46	49	pF

SWITCHING CHARACTERISTICS ⁽¹⁾

Symbol	Parameter	V _{CC} = 2.5V ± 0.2V		V _{CC} = 2.7V		V _{CC} = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PLH} t _{PHL}	Propagation Delay CLK to 1Bx or CLK to 2Bx	1.5	5	1.5	4.7	1.5	4.3	ns
t _{PLH} t _{PHL}	Propagation Delay CLK to Ax, SEL stable and $\overline{\text{CE}}\text{xB}$ enabled	1.5	5.3	1.5	5	1.5	4.6	ns
t _{PLH} t _{PHL}	Propagation Delay SEL changing and $\overline{\text{CE}}\text{xB}$ disabled	1.5	5.7	1.5	5.3	1.5	5.1	ns
t _{PLH} t _{PHL}	Propagation Delay SEL changing and $\overline{\text{CE}}\text{xB}$ enabled	1.5	5.8	1.5	5.4	1.5	5.1	ns
t _{PZH} t _{PZL}	Output Enable Time CLK to Ax, CLK to 1Bx, or CLK to 2Bx	1.5	5.6	1.5	5.2	1.5	5	ns
t _{PHZ} t _{PLZ}	Output Disable Time CLK to Ax, CLK to 1Bx, or CLK to 2Bx	1.3	4.7	1.5	5.2	1.5	5	ns
t _{SU}	Setup Time, data to CLK, HIGH or LOW	1	—	1	—	1	—	ns
t _{SU}	Setup Time, $\overline{\text{OE}}\text{A}$ to CLK, $\overline{\text{OE}}\text{B}$ to CLK	1	—	1	—	1	—	ns
t _{SU}	Setup Time, SEL to CLK	1	—	1	—	1	—	ns
t _{SU}	Setup Time, $\overline{\text{CE}}\text{A1B}$ to CLK, $\overline{\text{CE}}\text{1B}$ to CLK $\overline{\text{CE}}\text{2B}$ to CLK, or $\overline{\text{CE}}\text{A2B}$ to CLK	1	—	1	—	1	—	ns
t _H	Hold Time, CLK to data	1	—	1	—	1	—	ns
t _H	Hold Time, CLK to $\overline{\text{OE}}\text{A}$, CLK to $\overline{\text{OE}}\text{B}$, CLK to SEL	1	—	1	—	1	—	ns
t _H	Hold Time, CLK to $\overline{\text{CE}}\text{A1B}$, CLK to $\overline{\text{CE}}\text{1B}$, CLK to $\overline{\text{CE}}\text{2B}$, CLK to $\overline{\text{CE}}\text{A2B}$	1	—	1	—	1	—	ns
t _W	Pulse Width, CLK HIGH	2.5	—	2.5	—	2.5	—	ns
t _{sk(0)}	Output Skew ⁽²⁾	—	—	—	—	—	500	ps

NOTES:

- See test circuits and waveforms. T_A = – 40°C to + 85°C.
- Skew between any two outputs of the same package and switching in the same direction.

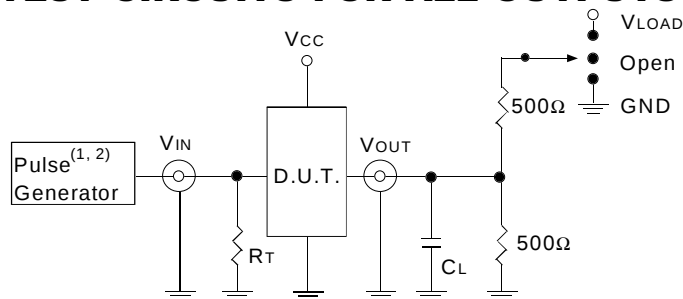
TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	V _{CC} (1)= 3.3V±0.3V	V _{CC} (1)= 2.7V	V _{CC} (2)= 2.5V±0.2V	Unit
V _{LOAD}	6	6	2 x V _{CC}	V
V _{IH}	2.7	2.7	V _{CC}	V
V _T	1.5	1.5	V _{CC} / 2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF

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TEST CIRCUITS FOR ALL OUTPUTS



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DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

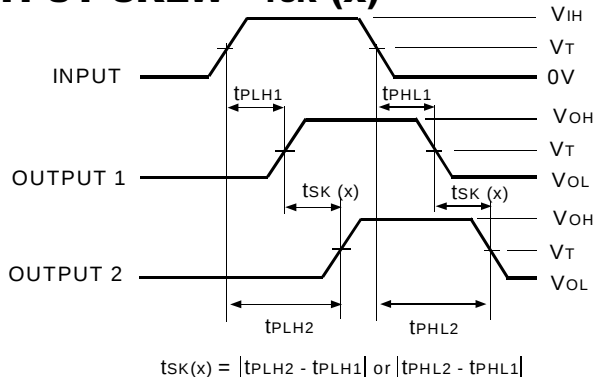
1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V _{LOAD}
Disable High Enable High	GND
All Other tests	Open

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OUTPUT SKEW - t_{SK} (x)



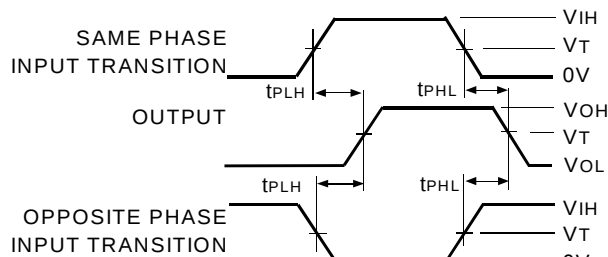
$$t_{SK}(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

ALVC Link

NOTES:

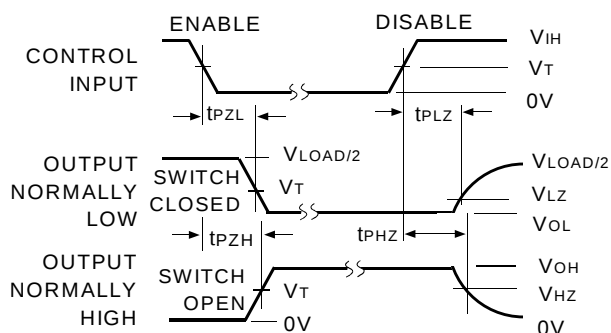
1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

PROPAGATION DELAY



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ENABLE AND DISABLE TIMES

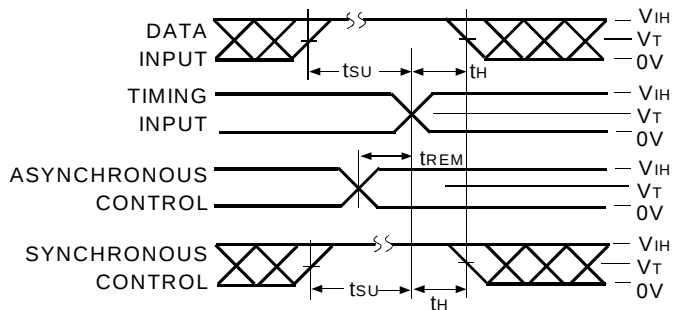


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NOTE:

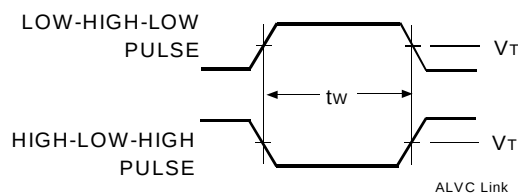
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD, AND RELEASE TIMES



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PULSE WIDTH



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ORDERING INFORMATION

IDT	XX	ALVC	X	XXX	XXX	XX	
Temp. Range			Bus-Hold	Family	Device Type	Package	
						PV	Shrink Small Outline Package (SO56-1)
						PA	Thin Shrink Small Outline Package (SO56-2)
						PF	Thin Very Small Outline Package (SO56-3)
					276		12-Bit Synchronous Bus Exchanger
				16			Double-Density with Resistors, $\pm 24\text{mA}$
			H				Bus-Hold
						74	-40°C to $+85^{\circ}\text{C}$



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